

# CMOS Static RAM 256K (32K x 8-Bit)

IDT71256S IDT71256L

#### **Features**

- High-speed address/chip select time
  - Military: 25/35/45/55/70/85/100ns (max.)
  - Commercial/Industrial: 20/25/35ns (max.) low power only
- Low-power operation
- Battery Backup operation 2V data retention
- Produced with advanced high-performance CMOS technology
- Input and output directly TTL-compatible
- Available in standard 28-pin (300 or 600 mil) ceramic DIP, 28-pin (300 mil) SOJ
- Military product compliant to MIL-STD-883, Class B

## **Description**

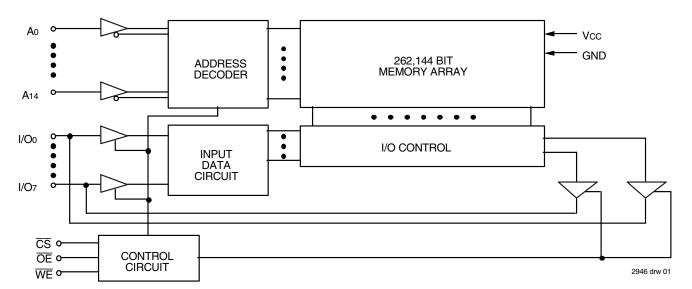
The IDT 71256 is a 262,144-bit high-speed static RAM organized as 32K x 8. It is fabricated using IDT's high-performance, high-reliability CMOS technology.

Address access times as fast as 20ns are available with power consumption of only 350 mW (typ.). The circuit also offers a reduced power standby mode. When  $\overline{CS}$  goes HIGH, the circuit will automatically go to and remain in, a low-power standby mode as long as  $\overline{CS}$  remains HIGH. In the full standby mode, the low-power device consumes less than  $15 \mu W$ , typically. This capability provides significant system level power and cooling savings. The low-power (L) version also offers a battery backup data retention capability where the circuit typically consumes only  $5 \mu W$  when operating off a 2V battery.

The IDT71256 is packaged in a 28-pin (300 or 600 mil) ceramic DIP, a 28-pin 300 mil SOJ providing high board level packing densities.

The IDT71256 military RAM is manufactured in compliance with the latest revision of MIL-STD-883, Class B, making it ideally suited to military temperature applications demanding the highest level of performance and reliability.

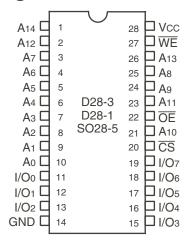
## **Functional Block Diagram**



**APRIL 2011** 

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## **Pin Configurations**



2946 drw 02

## DIP/SOJ Top View

## **Pin Descriptions**

| Name           | Description       |
|----------------|-------------------|
| A0 - A14       | Address Inputs    |
| I/O0 - I/O7    | Data Input/Output |
| <del>C</del> S | Chip Select       |
| WE             | Write Enable      |
| ŌĒ             | Output Enable     |
| GND            | Ground            |
| Vcc            | Power             |

2946 tbl 01

## Truth Table<sup>(1)</sup>

| WE | <u>cs</u> | Œ | I/O          | Function        |
|----|-----------|---|--------------|-----------------|
| Х  | Н         | Χ | High-Z       | Standby (IsB)   |
| Х  | Vнс       | Χ | High-Z       | Standby (ISB1)  |
| Н  | L         | Н | High-Z       | Output Disabled |
| Н  | L         | L | <b>D</b> out | Read Data       |
| L  | L         | Χ | DIN          | Write Data      |

NOTE:

2946 tbl 02

1. H = VIH, L = VIL, X = Don't care.

## **Absolute Maximum Ratings**(1)

| Symbol | Rating                               | Com'l.       | Ind.         | Mil.         | Unit |
|--------|--------------------------------------|--------------|--------------|--------------|------|
| VTERM  | Terminal Voltage with Respect to GND | -0.5 to +7.0 | -0.5 to +7.0 | -0.5 to +7.0 | V    |
| Та     | Operating<br>Temperature             | 0 to +70     | -40 to +85   | -55 to +125  | °C   |
| TBIAS  | Temperature<br>Under Bias            | -55 to +125  | -55 to +125  | -65 to +135  | °C   |
| Tstg   | Storage<br>Temperature               | -55 to +125  | -55 to +125  | -65 to +150  | °C   |
| Рт     | Power<br>Dissipation                 | 1.0          | 1.0          | 1.0          | W    |
| Іоит   | DC Output Current                    | 50           | 50           | 50           | mA   |

#### NOTE:

2946 tbl 03

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS
may cause permanent damage to the device. This is a stress rating only and
functional operation of the device at these or any other conditions above those
indicated in the operational sections of this specification is not implied. Exposure
to absolute maximum rating conditions for extended periods may affect
reliability.

## Capacitance ( $T_A = +25^{\circ}C$ , f = 1.0MHz)

| Symbol | Parameter <sup>(1)</sup> | Conditions | Max. | Unit |  |
|--------|--------------------------|------------|------|------|--|
| CIN    | Input Capacitance        | VIN = 0V   | 11   | pF   |  |
| Cvo    | I/O Capacitance          | Vout = 0V  | 11   | pF   |  |

NOTE:

 This parameter is determined by device characterization, but is not production tested

# Recommended Operating Temperature and Supply Voltage

| Grade      | Temperature     | GND | Vcc      |
|------------|-----------------|-----|----------|
| Military   | -55°C to +125°C | 0V  | 5V ± 10% |
| Industrial | -40°C to +85°C  | 0V  | 5V ± 10% |
| Commercial | 0°C to +70°C    | 0V  | 5V ± 10% |

2946 tbl 05

## Recommended DC Operating Conditions

| Symbol | Parameter          | Min.                | Тур. | Max. | Unit |
|--------|--------------------|---------------------|------|------|------|
| Vcc    | Supply Voltage     | 4.5                 | 5.0  | 5.5  | ٧    |
| GND    | Ground             | 0                   | 0    | 0    | ٧    |
| VIH    | Input High Voltage | 2.2                 | _    | 6.0  | ٧    |
| VIL    | Input Low Voltage  | -0.5 <sup>(1)</sup> | _    | 0.8  | ٧    |

2946 tbl 06

#### NOTE

1.  $V_{IL}$  (min.) = -3.0V for pulse width less than 20ns, once per cycle.

## **DC Electrical Characteristics** $^{(1,2)}$ (Vcc = 5.0V ± 10%, VLc = 0.2V, VHc = Vcc - 0.2V)

|  |  |       | (100 0101 = 1070, 1=0 |                |        |                 | ,     | 100 01217  |      |  |
|--|--|-------|-----------------------|----------------|--------|-----------------|-------|------------|------|--|
|  |  |       | 71256S/L20            | 71256          | SS/L25 | 71256           | S/L35 | 71256S/L45 |      |  |
| Symbol   | Parameter  | Power | Com'l.<br>& Ind       | Com'l<br>& Ind | Mil.   | Com'l.<br>& Ind | Mil.  | Mil.       | Unit |  |
| Icc  | ICC Dynamic Operating Current CS ≤ VIL, Outputs Open VCC = Max., fMax <sup>(2)</sup> | S     | _                     |                | 150    |                 | 140   | 135        | mA   |  |
|  |  | L     | 135                   | 125            | 130    | 115             | 120   | 115        |      |  |
| ISB  | Standby Power Supply Current   |       | _                     |                | 20     |                 | 20    | 20         | mA   |  |
| (TTL Level), $\overline{CS} \ge VIH$ , $Vcc = Max.$ ,<br>Outputs Open, $f = f_{Max}^{(2)}$ |  | L     | 3                     | 3              | 3      | 3               | 3     | 3          |      |  |
| ISB1   | Full Standby Power Supply Current  | S     | _                     |                | 20     |                 | 20    | 20         | mA   |  |
|  | (CMOS Level), $\overline{CS} \ge VHC$ ,<br>Vcc = Max., f = 0                         | L     | 0.6                   | 0.6            | 1.5    | 0.6             | 1.5   | 1.5        |      |  |

2946 tbl 07

|        |   |       | 71256S/L55 | 71256S/L70 | 71256S/L85 | 71256S/L100 |      |
|--------|---|-------|------------|------------|------------|-------------|------|
| Symbol | Parameter   | Power | Mil.       | Mil.       | Mil.       | Mil.        | Unit |
| Icc    | Dynamic Operating Current CS ≤ VIL, Outputs Open  | S     | 135        | 135        | 135        | 135         | mA   |
|        | Vcc = Max., fmax <sup>(2)</sup>   | L     | 115        | 115        | 115        | 115         |      |
| ISB    | Standby Power Supply Current  | S     | 20         | 20         | 20         | 20          | mA   |
|        | Standby Power Supply Current (TTL Level), $\overline{CS} \ge VIH$ , $VCC = Max.$ , Outputs Open, $f = fmax^{(2)}$ | L     | 3          | 3          | 3          | 3           |      |
| ISB1   | Full Standby Power Supply Current   | S     | 20         | 20         | 20         | 20          | mA   |
|        | (CMOS Level), $\overline{CS} \ge VHC$ ,<br>VCC = Max., f = 0  | L     | 1.5        | 1.5        | 1.5        | 1.5         |      |

2946 tbl 08

NOTES:

1. All values are maximum guaranteed values.

2. fmax = 1/trc, all address inputs are cycling at fmax; f = 0 means no address pins are cycling.

#### **AC Test Conditions**

| Input Pulse Levels            | GND to 3.0V         |
|-------------------------------|---------------------|
| Input Rise/Fall Times         | 5ns                 |
| Input Timing Reference Levels | 1.5V                |
| Output Reference Levels       | 1.5V                |
| AC Test Load                  | See Figures 1 and 2 |

2946 tbl 09

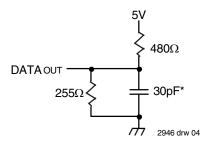


Figure 1. AC Test Load

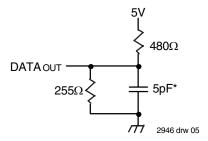


Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

\*Includes scope and jig capacitances

## DC Electrical Characteristics (Vcc = 5.0V ± 10%)

|        |                        |   |                      | IDT71256S |      |         |      |      |        |      |
|--------|------------------------|---|----------------------|-----------|------|---------|------|------|--------|------|
| Symbol | Parameter              | Test Conditions   |                      | Min.      | Тур. | Max.    | Min. | Тур. | Max.   | Unit |
| ILI    | Input Leakage Current  | Vcc = Max.,<br>Vin = GND to Vcc                         | MIL.<br>COM"L & IND. |           |      | 10<br>5 |      |      | 5<br>2 | μΑ   |
| lLO    | Output Leakage Current | VCC = Max., $\overline{CS}$ = VIH,<br>VOUT = GND to VCC | MIL.<br>COM"L & IND. |           |      | 10<br>5 |      |      | 5<br>2 | μΑ   |
| Vol    | Output Low Voltage     | IoL = 8mA, Vcc = Min.                                   |                      |           |      | 0.4     |      |      | 0.4    | V    |
|        |                        | IoL = 10mA, Vcc = Min.                                  |                      |           |      | 0.5     | _    |      | 0.5    |      |
| Voн    | Output High Voltage    | IOH = -4mA, Vcc = Min.                                  |                      | 2.4       |      |         | 2.4  |      |        | V    |

2946 tbl 10

## Data Retention Characteristics Over All Temperature Ranges (L Version Only) (VLc = 0.2V, VHc = Vcc - 0.2V)

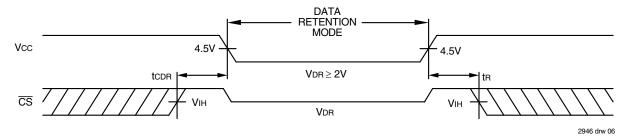
|                   |   |                    |                       |          |          | p. <sup>(1)</sup><br>c @ |            | ax.<br>c @ |      |
|-------------------|---|--------------------|-----------------------|----------|----------|--------------------------|------------|------------|------|
| Symbol            | Parameter                               | Tes                | Test Condition        |          | 2.0V     | 3.0V                     | 2.0V       | 3.0V       | Unit |
| VDR               | Vcc for Data Retention                  |                    |                       | 2.0      | _        | _                        | _          | _          | V    |
| ICCDR             | Data Retention Current                  |                    | MIL.<br>COM'L. & IND. | <u> </u> | <u> </u> | _                        | 500<br>120 | 800<br>200 | μА   |
| todr              | Chip Deselect to Data<br>Retention Time | <u>CS &gt;</u> Vно |                       | 0        | _        | _                        | _          |            | ns   |
| tR <sup>(3)</sup> | Operation Recovery Time                 |                    |                       | trc(2)   | _        | _                        | _          | _          | ns   |

#### NOTES:

- 1. TA = +25°C.
- 2. tRC = Read Cycle Time.
- 3. This parameter is guaranteed by device characterization, but is not production tested.

2946 tbl 11

## **Low Vcc Data Retention Waveform**



AC Electrical Characteristics (Vcc = 5.0V ± 10%, All Temperature Ranges)

|                     |                                    | 7125 | 6L20 <sup>(1)</sup> |      | 71256S25 <sup>(3)</sup><br>71256L25 |      | 71256S35 <sup>(3)</sup><br>71256L35 |      | 71256S45 <sup>(3)</sup><br>71256L45 <sup>(3)</sup> |      |
|---------------------|------------------------------------|------|---------------------|------|-------------------------------------|------|-------------------------------------|------|--|------|
| Symbol              | Parameter                          | Min. | Max.                | Min. | Max.                                | Min. | Max.                                | Min. | Max.   | Unit |
| Read Cy             | rcle                               | •    | •                   | •    | •                                   |      |                                     | •    |  | •    |
| trc                 | Read Cycle Time                    | 20   | _                   | 25   | _                                   | 35   | _                                   | 45   | _  | ns   |
| taa                 | Address Access Time                | _    | 20                  | _    | 25                                  | _    | 35                                  | _    | 45   | ns   |
| tacs                | Chip Select Access Time            | _    | 20                  |      | 25                                  | _    | 35                                  | _    | 45   | ns   |
| tclz <sup>(2)</sup> | Chip Select to Output in Low-Z     | 5    | _                   | 5    | _                                   | 5    | _                                   | 5    | _  | ns   |
| tchz <sup>(2)</sup> | Chip Deselect to Output in High-Z  | _    | 10                  | _    | 11                                  |      | 15                                  | _    | 20   | ns   |
| toE                 | Output Enable to Output Valid      | _    | 10                  | _    | 11                                  | _    | 15                                  | _    | 20   | ns   |
| tolz <sup>(2)</sup> | Output Enable to Output in Low-Z   | 2    | _                   | 2    | _                                   | 2    | _                                   | 0    | _  | ns   |
| tohz <sup>(2)</sup> | Output Disable to Output in High-Z | 2    | 8                   | 2    | 10                                  | 2    | 15                                  | _    | 20   | ns   |
| tон                 | Output Hold from Address Change    | 5    | _                   | 5    | _                                   | 5    |                                     | 5    |  | ns   |
| Write Cy            | /cle                               | •    | •                   | •    | •                                   | •    | •                                   | •    |  | •    |
| twc                 | Write Cycle Time                   | 20   | _                   | 25   | _                                   | 35   | _                                   | 45   | _  | ns   |
| tcw                 | Chip Select to End-of-Write        | 15   | _                   | 20   |                                     | 30   | _                                   | 40   | _  | ns   |
| taw                 | Address Valid to End-of-Write      | 15   | _                   | 20   |                                     | 30   |                                     | 40   | _  | ns   |
| tas                 | Address Set-up Time                | 0    | _                   | 0    |                                     | 0    |                                     | 0    | _  | ns   |
| twp                 | Write Pulse Width                  | 15   | _                   | 20   | _                                   | 30   |                                     | 35   | _  | ns   |
| twr                 | Write Recovery Time                | 0    | _                   | 0    | _                                   | 0    |                                     | 0    | _  | ns   |
| tow                 | Data to Write Time Overlap         | 11   | _                   | 13   | _                                   | 15   | _                                   | 20   | _  | ns   |
| twhz <sup>(2)</sup> | Write Enable to Output in High-Z   |      | 10                  |      | 11                                  | _    | 15                                  | _    | 20   | ns   |
| tDH                 | Data Hold from Write Time          | 0    | _                   | 0    | _                                   | 0    | _                                   | 0    | _  | ns   |
| tow <sup>(2)</sup>  | Output Active from End-of-Write    | 5    |                     | 5    | _                                   | 5    |                                     | 5    | _  | ns   |

#### NOTES:

2946 tbl 12

- 1. 0° to +70°C or -40° to +85°C temperature range only.
- 2. This parameter is guaranteed by device characterization, but is not production tested.
- 3. -55°C to +125°C temperature range only.

## **AC Electrical Characteristics** (Vcc = 5.0V ± 10%, Military Temperature Ranges)

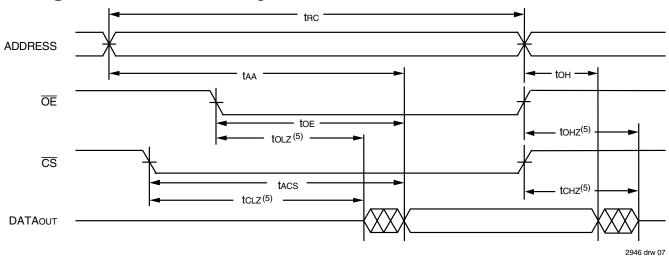
|                     |                                    | 71256<br>71256 | SS55 <sup>(1)</sup><br>SL55 <sup>(1)</sup> | 71256S70 <sup>(1)</sup><br>71256L70 <sup>(1)</sup> |      | 71256\$85 <sup>(1)</sup><br>71256L85 <sup>(1)</sup> |      | 71256S100 <sup>(1)</sup><br>71256L100 <sup>(1)</sup> |      |      |
|---------------------|------------------------------------|----------------|--|--|------|---|------|--|------|------|
| Symbol              | Parameter                          | Min.           | Max.                                       | Min.   | Max. | Min.  | Max. | Min.   | Max. | Unit |
| Read Cy             | Read Cycle                         |                |  |  |      |   |      |  |      |      |
| trc                 | Read Cycle Time                    |                | _  | 70   | _    | 85  |      | 100  |      | ns   |
| taa                 | Address Access Time                |                | 55   |  | 70   |   | 85   |  | 100  | ns   |
| tacs                | Chip Select Access Time            |                | 55   |  | 70   |   | 85   |  | 100  | ns   |
| talz(2)             | Chip Select to Output in Low-Z     | 5              | _  | 5  | _    | 5   |      | 5  |      | ns   |
| tcHz <sup>(2)</sup> | Chip Deselect to Output in High-Z  |                | 25   | _  | 30   | _   | 35   | _  | 40   | ns   |
| toE                 | Output Enable to Output Valid      | _              | 25   | _  | 30   |   | 35   | _  | 40   | ns   |
| toLz <sup>(2)</sup> | Output Enable to Output in Low-Z   | 0              | _  | 0  | _    | 0   |      | 0  |      | ns   |
| tonz <sup>(2)</sup> | Output Disable to Output in High-Z | 0              | 25   | 0  | 30   | _   | 35   | _  | 40   | ns   |
| tон                 | Output Hold from Address Change    | 5              | _  | 5  | _    | 5   |      | 5  |      | ns   |
| Write Cycle         |                                    |                |  |  |      |   |      |  |      |      |
| twc                 | Write Cycle Time                   | 55             | _  | 70   |      | 85  |      | 100  |      | ns   |
| tcw                 | Chip Select to End-of-Write        | 50             | _  | 60   | _    | 70  |      | 80   |      | ns   |
| taw                 | Address Valid to End-of-Write      |                | _  | 60   | _    | 70  |      | 80   |      | ns   |
| tas                 | Address Set-up Time                |                |  | 0  |      | 0   |      | 0  |      | ns   |
| twp                 | Write Pulse Width                  |                |  | 45   |      | 50  |      | 55   |      | ns   |
| twr                 | Write Recovery Time                |                |  | 0  |      | 0   |      | 0  |      | ns   |
| tow                 | Data to Write Time Overlap         |                |  | 30   |      | 35  |      | 40   |      | ns   |
| twnz <sup>(2)</sup> | Write Enable to Output in High-Z   |                | 25   |  | 30   |   | 35   |  | 40   | ns   |
| tон                 | Data Hold from Write Time (WE)     |                |  | 0  | _    | 0   | _    | 0  |      | ns   |
| tow <sup>(2)</sup>  | Output Active from End-of-Write    | 5              |  | 5  |      | 5   |      | 5  |      | ns   |

#### NOTES:

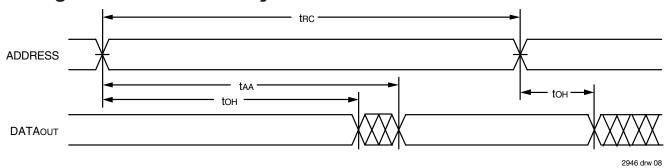
2946 tbl 13

 <sup>-55°</sup> to +125°C temperature range only.
 This parameter is guaranteed by device characterization, but is not production tested.

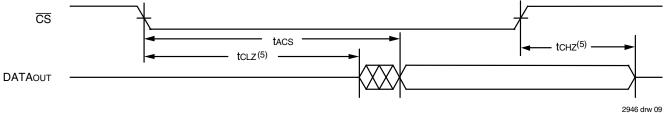
## Timing Waveform of Read Cycle No. 1(1)



## Timing Waveform of Read Cycle No. 2<sup>(1,2,4)</sup>



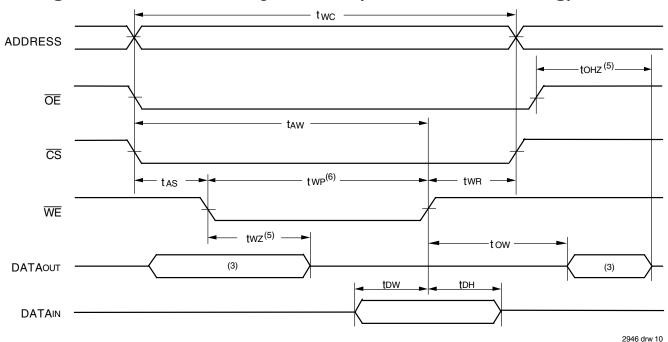
## Timing Waveform of Read Cycle No. 2<sup>(1,3,4)</sup>



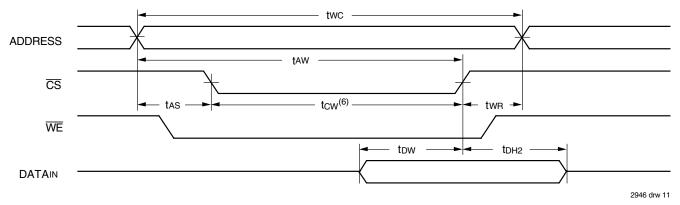
#### NOTES:

- 1. WE is HIGH for Read Cycle.
- 2. Device is continuously selected,  $\overline{\text{CS}}$  is LOW.
- 3. Address valid prior to or coincident with  $\overline{\text{CS}}$  transition LOW.
- 4.  $\overline{\text{OE}}$  is LOW.
- 5. Transition is measured ±200mV from steady state.

## Timing Waveform of Write Cycle No. 1 (WE Controlled Timing)(1,2,4,6)



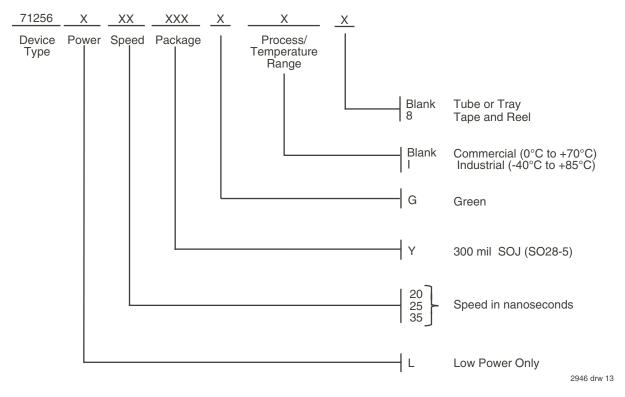
## Timing Waveform of Write Cycle No. 2 (CS Controlled Timing)(1,2,4)



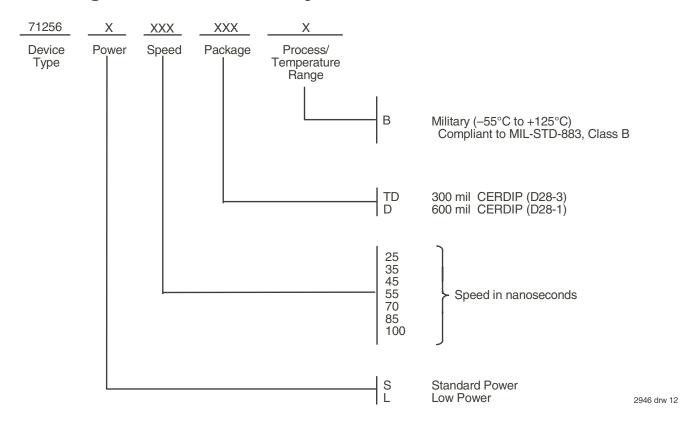
#### NOTES:

- 1. A write occurs during the overlap of a LOW  $\overline{\text{CS}}$  and a LOW  $\overline{\text{WE}}$ .
- 2. twn is measured from the earlier of  $\overline{\text{CS}}$  or  $\overline{\text{WE}}$  going HIGH to the end of the write cycle.
- 3. During this period, I/O pins are in the output state so that the input signals must not be applied.
- 4. If the CS LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.
- 6. If  $\overline{OE}$  is LOW during a  $\overline{WE}$  controlled write cycle, the write pulse width must be the larger of twp or (twHz +tbw) to allow the I/O drivers to turn off and data to be placed on the bus for the required tbw. If  $\overline{OE}$  is HIGH during a  $\overline{WE}$  controlled write cycle, this requirement does not apply and the minimum write pulse width can be as short as the specified twp. For a CS controlled write cycle,  $\overline{OE}$  may be LOW with no degradation to tcw.

## **Ordering Information — Commercial & Industrial**



## **Ordering Information — Military**



## **Datasheet Document History**

| 11/4/99  |                | Updated to new format  |
|----------|----------------|--|
|          | Pp. 1–5, 9     | Added Industrial Temperature Range offerings   |
|          | Pg. 1          | Removed 30, 120, and 150ns military and 45ns commercial speed grade offerings.                                   |
|          | Pg. 2          | Removed P28-2 package from DIP/SOJ Top View  |
|          | Pg. 3          | Removed 30ns and 45ns (Commercial only) speed grade offerings from DC Electrical table                           |
|          | 1 g. 5         | Revised notes and footnotes  |
|          | Da 5           |  |
|          | Pg. 5          | Removed 30ns speed grade offering from AC Electrical table Revised notes and footnotes                           |
|          | D. C           |  |
|          | Pg. 6          | Expressed Military Temperature range on AC Electrical table  |
|          |                | Revised notes and footnotes  |
|          | Pg. 8          | Removed Note 1 and renumbered notes and footnotes  |
|          | Pg. 9          | Revised Ordering Information and presented by temperature range offering   |
|          | Pg. 10         | Added Datasheet Document History   |
| 08/09/00 |                | Not recommended for new designs  |
| 02/01/01 |                | Remove "Not recommended for new designs"   |
|          |                |  |
| 11/15/06 | Pg.3           | Changed power limits for commercial and industrial. Refer to PCN SR-0602-03. Added Restricted hazardous          |
|          |                | substance devce to ordering information.   |
| 11/01/08 | Da 2.0         | Corrected type on pin 21 in 22 Din LCC diagram. Undated the ordering information by removing the                 |
| 11/01/06 | Pg.2,9         | Corrected typo on pin 21 in 32-Pin LCC diagram. Updated the ordering information by removing the "IDT" notation. |
| 04/28/11 | Pg. 1, 2, 5, 9 | Added 20ns to Industrial offering. Obsoleted 28-pin 600 mil, 32-pin LCC and Added Tape and Reel to               |
|          | -              | Ordering information and updated description of Restricted hazardous substance device to Green.                  |



CORPORATE HEADQUARTERS 6024 Silver Creek Valley Road San Jose, CA 95138

for SALES: 800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com

for Tech Support: ipchelp@idt.com 800-345-7015

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